

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUS300N10S5N015T	**Issued**	15. May 2021
MA#	MA005344600		
Package	PG-HDSOP-16-2	**Weight***	855.62 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.727	0.90	0.90	9031	9031
leadframe	inorganic material	phosphorus	7723-14-0	0.143	0.02		167	
	non noble metal	iron	7439-89-6	0.477	0.06		558	
	non noble metal	copper	7440-50-8	476.748	55.72	55.80	557198	557923
wire	non noble metal	aluminium	7429-90-5	20.885	2.44	2.44	24409	24409
encapsulation	inorganic material	zincoxide	1314-13-2	3.226	0.38		3770	
	miscellaneous	miscellaneous	-	12.902	1.51		15080	
	plastics	epoxy resin	-	48.384	5.65		56549	
	inorganic material	silicondioxide	60676-86-0	258.047	30.16	37.70	301592	376991
leadfinish	non noble metal	tin	7440-31-5	6.684	0.78	0.78	7812	7812
plating	inorganic material	phosphorus	7723-14-0	0.013			15	
	non noble metal	nickel	7440-02-0	5.316	0.62	0.62	6213	6228
solder	non noble metal	tin	7440-31-5	0.125	0.01		146	
	noble metal	silver	7440-22-4	0.156	0.02		183	
	non noble metal	lead	7439-92-1	5.973	0.70	0.73	6981	7310
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			3	
	non noble metal	iron	7439-89-6	0.009			10	
	non noble metal	copper	7440-50-8	8.798	1.03	1.03	10283	10296
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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